

ABSTRACT OF THE DISCLOSURE

A semiconductor package includes a substrate having a top surface and a bottom surface; at least one chip mounted on the top surface of the substrate and electrically connected to the substrate; a heat sink attached to the top surface of the substrate by an adhesive material applied therebetween; and a plurality of solder balls implanted on the bottom surface of the substrate. The heat sink has a flat portion and a support portion connected to the flat portion. The support portion has at least one recess portion facing toward the top surface of the substrate and at least one burr formed on an interior surface of the recess portion such that the adhesive material can fill the recess portion and submerge the burr to provide an anchoring effect to firmly secure the heat sink in position on the substrate.

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